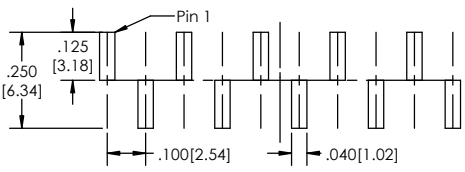
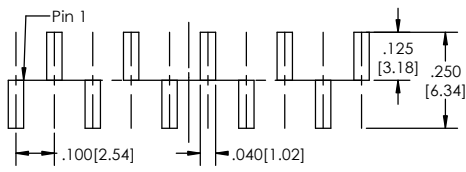


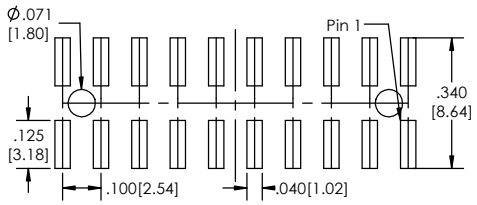
Recommended P.C. Board Layout
SCALE 4:1



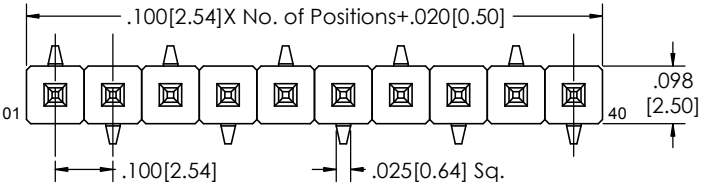
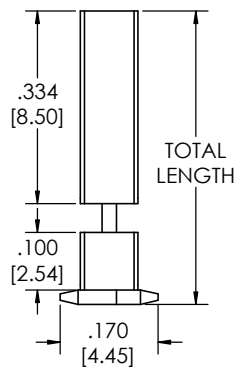
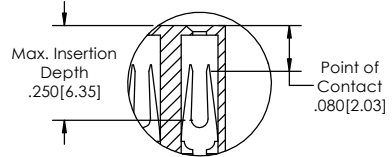
SINGLE (M) ROW



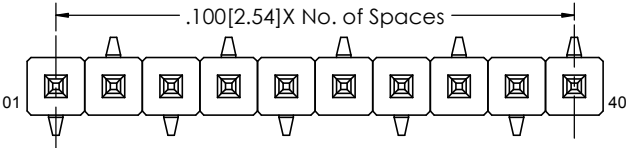
SINGLE (S) ROW



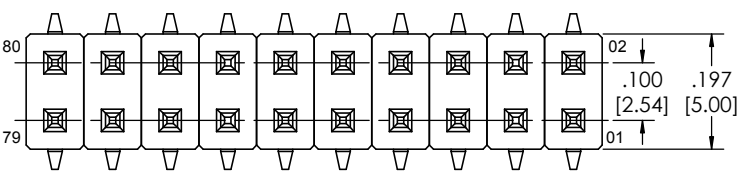
DOUBLE ROW



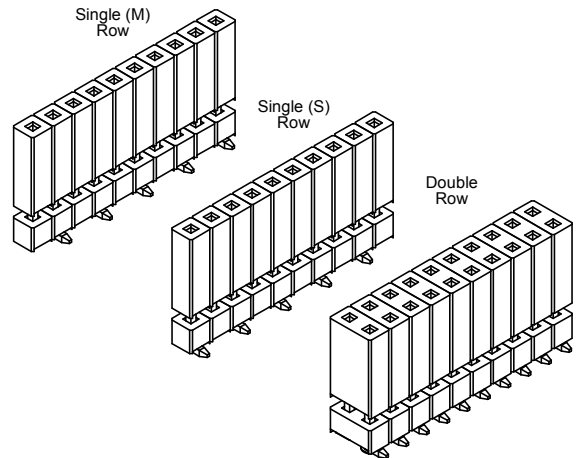
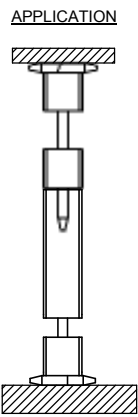
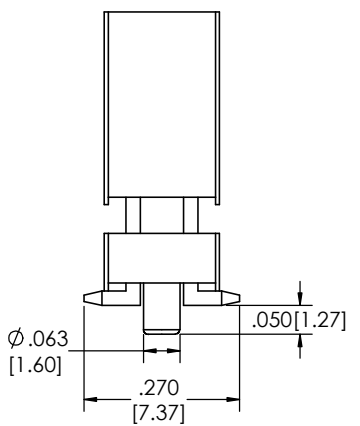
SINGLE ROW (M)



SINGLE ROW (S)



DOUBLE ROW



BSSQM-1 **XX** - **X** - **XX** - **X** - **XXX** - **XXX** - **X** - **XX** - **X** - **XX** - **X**
(A) **(B)** **(C)** **(D)** **(E)** **(F)** **(G)** **(H)** **(I)** **(J)** **(K)**

- A. Pins Per Row - 02 through 40
- B. Row Specification - S= Single Row, D= Double Row
- C. Pin Options - See Pin Options Below
- D. Plating Options - See Plating Options below
- E. Desired Board Space - Please Specify required space - E.g. .100[2.54]=100
- F. Polarized Position - Leave blank if not needed - If required, specify empty pin position, e.g. 012 for Pin 12
- G. Footprint - S= Pin 1 right, M= Pin 1 left
- H. Packing Information - TR= Tape and Reel, TB= Tube
- I. Pad - P= Pad, O= No Pad - If left blank, packaging at MLE's discretion - Pad may be metal, mylar or plastic
- J. Alignment Pin Option - Leave blank if not needed - AP= With
- K. Lead Free

- Mates with:**
- BSTC TSHCR
 - BSTCM TSHCRE
 - BSTCR TSHCRSM
 - BSTCRSM TSHR
 - BSTS TSHRE
 - LBSTCM TSHS
 - LTSHCR TSHSCM
 - LTSHCR TSHS
 - LTSHCRE TSHSM
 - LTSHR ULTSHSM
 - LTSHRE ULTSHC
 - LTSHSM ULTSHCR
 - TSHC

Specifications:
 Insertion Depth: .145(3.68) to .250(6.35)
 Insertion Force- Per Contact- H Plating:
 6oz. (1.67N) avg with .025(0.64mm) sq. pin
 Withdrawal Force- Per Contact- H Plating:
 5oz. (1.39N) avg with .025(0.64mm) sq. pin
 Current Rating: 3.0 Ampere
 Insulation Resistance: 1000M Ohms Min.
 Dielectric Withstanding: 600V AC
 Contact Resistance: 20M Ohms Max.
 Operation Temperature: -40°C to +105°C
 Max. Process Temperature
 Peak: 260°C up to 20 secs.
 Process: 230°C up to 60 secs.
 Wave: 260°C up to 6 secs.
 Manual Solder: 350°C up to 5 secs.

Pin Options	
Max. Board Space	02
.455[11.56]	04
.655[16.67]	06
.855[21.72]	

Board Space must not exceed maximum pin option

Plating options	
G	-10µ Gold on Contact Area/ Flash on Tail
T	-Matte Tin all Over
GT	-10µ Gold on Contact Area/ Matte Tin on Tail
H	-30µ Gold on Contact Area/ Matte Tin on Tail
F	-Gold Flash over Entire Pin
FT	- Gold Flash on Contact Area/ Matte Tin on Tail

Materials:
 Contact Material: Phosphor Bronze
 Insulator Material: Nylon 6T
 Plating: Au or Sn over 50µ" (1.27) Ni
 Tails may be clipped to achieve specific dimensions.
 Products cut to specific sizes are uncancellable/ nonreturnable.
 Parts are subject to change without notice.



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UNLESS OTHERWISE SPECIFIED:		NAME	DATE
DIMENSIONS ARE IN INCHES		EOW	01/20/15
TOLERANCES:		CHECKED	GWE
ONE DECIMALS ±.100		ENG APPR.	
TWO DECIMAL ±.100		MFG APPR.	
THREE DECIMAL ±.005		ADDRESS	
FOUR DECIMAL ±.002		2533 Centennial Blvd. Jeffersonville, In 47130 Phone: 812-670-4174 Fax: 812-670-4175 E-Mail: mle@mlelectronics.com	
NEXT ASSY	USED ON	TITLE: BSSQM-1 Series	
APPLICATION	DO NOT SCALE DRAWING	SIZE DWG. NO.	REV
		C	C
		SCALE 6:1	SHEET 1 OF 1

